

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	702	sandblasting and semiconductor	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/06 19:08
S2	96	("4907062" "5279681" "5326670" "6060402" "6089966" "4613400" "5219783" "5256563" "5296385" "5403700" "5407485" "5426016" "5476819" "5503285" "5617340" "5643839" "5672894" "5767002" "5798293" "5840199" "5850042" "6022586" "6133582" "4342817" "4417946" "4456490" "4759990" "4791586" "4859633" "4871630" "4906314" "4928626" "5199483" "5275695" "5281473" "5450332" "5451886" "5473433" "5551986" "5605499" "5612253" "5650639" "5685906" "5688358" "5702867" "5756242" "5763124" "5773174" "5863659" "5866436").pn.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/09 17:15
S3	0	S1 and S2	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/09 17:12
S4	258	sandblasting and semiconductor and resin	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/09 17:12
S5	11	sandblasting and semiconductor and resin and wiring adj pattern	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/09 17:13
S6	3605	Hanaoka.in.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/09 17:16
S7	25	Hanaoka-terunao.in.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/09 17:16
S8	13	("5470787" "5767010" "5886415" "6097087" "6287893" "6313532" "6326701" "6333565" "6348730" "6373131" "6380620" "6388335" "6389689").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/05/09 17:27

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S9	7	("6333565").URPN.	USPAT	OR	OFF	2005/05/09 17:30
S10	0	wiring adj pattern and interconnect and external adj terminal and resin and mask adj layer	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 14:04
S11	11	wiring adj pattern and interconnect and external adj terminal and resin	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/12 14:04
S12	58381	wiring and insulating adj (film or layer)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 10:16
S13	72448	wiring and insulating adj (film or layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 10:16
S14	17921	wiring and insulating adj (film or layer) and resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 10:17
S15	1084	wiring and insulating adj (film or layer) and resin and interconnect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 10:23
S16	51	wiring and insulating adj (film or layer) and resin and interconnect and sandblasting	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 10:18
S17	873	wiring and insulating adj (film or layer) and resin and interconnect and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 10:32
S18	0	wiring and insulating adj (film or layer) and resin and interconnect and semiconductor and sanblasting	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 11:29
S19	2	"6891248".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 11:49

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S20	2003	438/107	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/06 19:16
S21	2003	438/107	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2005/10/25 11:50
S22	2003	438/107	US-PGPUB; USPAT; DERWENT; IBM_TDB	OR	ON	2005/10/25 12:07
S23	0	"63333565".pn.	US-PGPUB; USPAT; DERWENT; IBM_TDB	OR	ON	2005/10/25 12:08
S24	2	"6333565".pn.	US-PGPUB; USPAT; DERWENT; IBM_TDB	OR	ON	2005/10/25 13:01
S25	1404	438/108.ccls.	US-PGPUB; USPAT; DERWENT; IBM_TDB	OR	ON	2006/04/06 19:16
S26	770	438/109.ccls.	US-PGPUB; USPAT; DERWENT; IBM_TDB	OR	ON	2006/04/06 19:16
S27	842	438/113.ccls.	US-PGPUB; USPAT; DERWENT; IBM_TDB	OR	ON	2006/04/06 19:18
S28	1	("6633081").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/25 15:18
S29	873	438/460.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/06 19:18
S30	2	"6333565".pn.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/26 17:22
S31	3	("20020008320" "6707153").PN.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/06 19:08

EAST Search History

S32	1248	438/107.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 12:05
S33	1530	438/108.ccls.	US-PGPUB; USPAT; DERWENT; IBM_TDB	OR	ON	2006/08/03 12:06
S34	839	438/109.ccls.	US-PGPUB; USPAT; DERWENT; IBM_TDB	OR	ON	2006/08/03 12:06
S35	902	438/113.ccls.	US-PGPUB; USPAT; DERWENT; IBM_TDB	OR	ON	2006/08/03 12:06
S36	951	438/460.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/08/03 12:06
S37	255	438/114.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/11 09:47
S38	50	("4907062" "5279681" "5326670" "6060402" "6089966" "4613400" "5219783" "5256563" "5296385" "5403700" "5407485" "5426016" "5476819" "5503285" "5617340" "5643839" "5672894" "5767002" "5798293" "5840199" "5850042" "6022586" "6133582" "4342817" "4417946" "4456490" "4759990" "4791586" "4859633" "4871630" "4906314" "4928626" "5199483" "5275695" "5281473" "5450332" "5451886" "5473433" "5551986" "5605499" "5612253" "5650639" "5685906" "5688358" "5702867" "5756242" "5763124" "5773174" "5863659" "5866436").pn.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/06 19:24
S39	258	438/114.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/11 09:47
S40	952	438/460.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/08/03 12:06
S41	1	"6897127".pn.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/11 11:53

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S42	1	("6633081").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/04/11 11:53
S43	1	("6897127").URPN.	USPAT	OR	OFF	2006/04/11 11:56
S44	1300	438/107.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 12:05
S45	1623	438/108.ccls.	US-PGPUB; USPAT; DERWENT; IBM_TDB	OR	ON	2006/08/03 12:06
S46	903	438/109.ccls.	US-PGPUB; USPAT; DERWENT; IBM_TDB	OR	ON	2006/08/03 12:06
S47	952	438/113.ccls.	US-PGPUB; USPAT; DERWENT; IBM_TDB	OR	ON	2006/08/03 12:06
S48	1018	438/460.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/08/03 12:06
S49	1018	438/460.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/08/03 12:19
S50	1568	resin adj layer and Cut\$4 same semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 12:21
S51	942	resin adj layer and Cut\$4 same semiconductor and (ball or bump)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/03 12:26